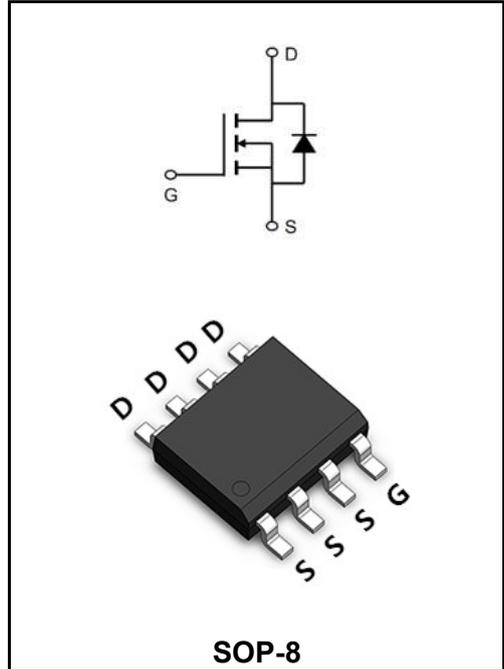


**100V N-CHANNEL ENHANCEMENT MODE MOSFET**

**MAIN CHARACTERISTICS**

<b>I<sub>D</sub></b>	12.3A
<b>V<sub>DSS</sub></b>	100V
<b>R<sub>DS(on)-typ(@V<sub>GS</sub>=10V)</sub></b>	< 110mΩ( <b>Type:93 mΩ</b> )



**Application**

- ◆Automotive lighting
- ◆Load switch
- ◆PSE

**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Symbols	Value	Units
Drain-Source Voltage	<b>V<sub>DS</sub></b>	100	<b>V</b>
Gate - Source Voltage	<b>V<sub>GS</sub></b>	±20	<b>V</b>
Drain Current, V <sub>GS</sub> @ 10V @T <sub>C</sub> =25°C	<b>I<sub>D</sub></b>	12.3	<b>A</b>
Drain Current, V <sub>GS</sub> @ 10V @T <sub>C</sub> =100°C	<b>I<sub>D</sub></b>	6.5	<b>A</b>
Pulsed Drain Current <sup>1</sup>	<b>I<sub>DM</sub></b>	24	<b>A</b>
Total Power Dissipation @T <sub>C</sub> =25°C	<b>P<sub>D</sub></b>	30	<b>W</b>
Total Power Dissipation <sup>3</sup> @T <sub>A</sub> =25°C	<b>P<sub>D</sub></b>	2.7	<b>W</b>
Storage Temperature Range	<b>T<sub>STG</sub></b>	-55 to +150	<b>°C</b>
Operating Junction Temperature Range	<b>T<sub>J</sub></b>	-55 to +150	<b>°C</b>
Maximum Thermal Resistance, Junction ambient	<b>R<sub>θJA</sub></b>	85	<b>°C/W</b>
Maximum Thermal Resistance, Junction-case	<b>R<sub>θJC</sub></b>	5.1	<b>°C/W</b>

**Maximum Ratings at Tc=25°C unless otherwise specified**

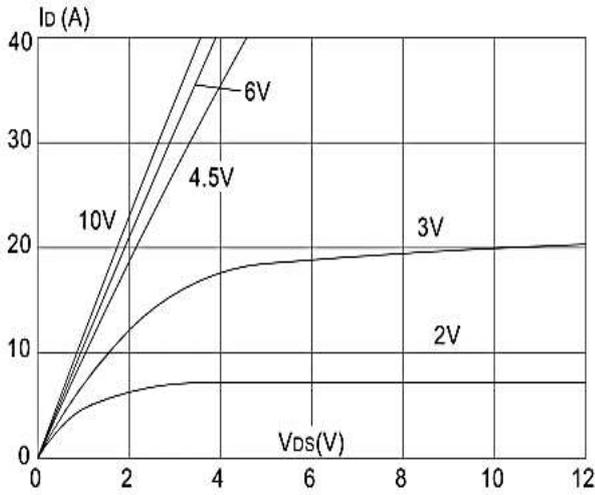
Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	<b>V(BR)DSS</b>	100	107	-	<b>V</b>
Zero Gate Voltage Drain Current	$V_{DS}=100V, V_{GS}=0V$	<b>I<sub>DSS</sub></b>	-	-	1.0	<b>μA</b>
Gate to Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	<b>I<sub>GSS</sub></b>	-	-	±100	<b>nA</b>
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	<b>V<sub>GS(th)</sub></b>	1.0	1.5	2.5	<b>V</b>
Static Drain-Source on-Resistance	$V_{GS}=10V, I_D=5A$	<b>R<sub>DS(on)</sub></b>	-	93	110	<b>mΩ</b>
	$V_{GS}=4.5V, I_D=3A$		-	100	140	
Input Capacitance	$V_{DS}=25V$ $V_{GS}=0V$ $f=1.0MHz$	<b>C<sub>iss</sub></b>	-	645	-	<b>pF</b>
Output Capacitance		<b>C<sub>oss</sub></b>	-	38	-	
Reverse Transfer Capacitance		<b>C<sub>rss</sub></b>	-	33	-	
Total Gate Charge	$V_{DS}=30V$ $V_{GS}=10V$ $I_D=5A$	<b>Q<sub>g</sub></b>	-	12	-	<b>nC</b>
Gate-Source Charge		<b>Q<sub>gs</sub></b>	-	2.2	-	
Gate-Drain("Miller") Charge		<b>Q<sub>gd</sub></b>	-	2.5	-	
Turn-on delay time	$V_{DS}=30V$ $I_D=10A$ $R_G=1.8\Omega$ $V_{GS}=10V$	<b>t<sub>d(on)</sub></b>	-	7	-	<b>ns</b>
Turn-on Rise Time		<b>T<sub>r</sub></b>	-	5	-	
Turn-Off Delay Time		<b>t<sub>d(OFF)</sub></b>	-	16	-	
Turn-Off Fall Time		<b>t<sub>f</sub></b>	-	6	-	
Maximum Continuous Drain to Source Diode Forward Current		<b>I<sub>S</sub></b>	-	-	10	<b>A</b>
Maximum Pulsed Drain to Source Diode Forward Current		<b>I<sub>SM</sub></b>	-	-	40	<b>A</b>
Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=10A$	<b>V<sub>SD</sub></b>	-	-	1.2	<b>V</b>
Body Diode Reverse Recovery Time	$I_F=10A, dI/dt=100A/\mu s$	<b>t<sub>rr</sub></b>	-	21	-	<b>ns</b>
Body Diode Reverse Recovery Charge		<b>Q<sub>rr</sub></b>	-	21	-	<b>nC</b>

Note :

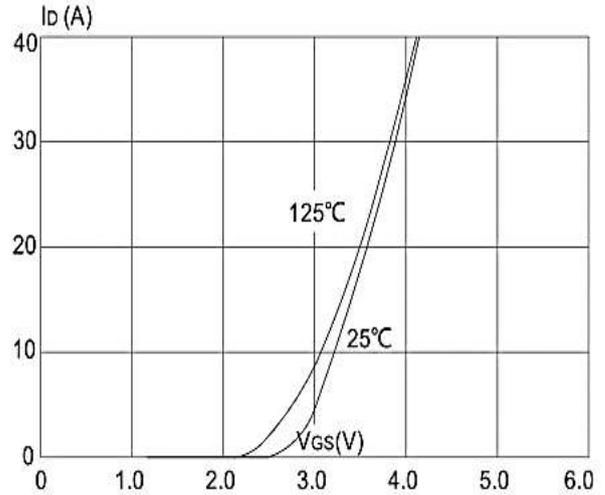
- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3、 The power dissipation is limited by 150°C junction temperature
- 4、 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

**Ratings and Characteristic Curves**

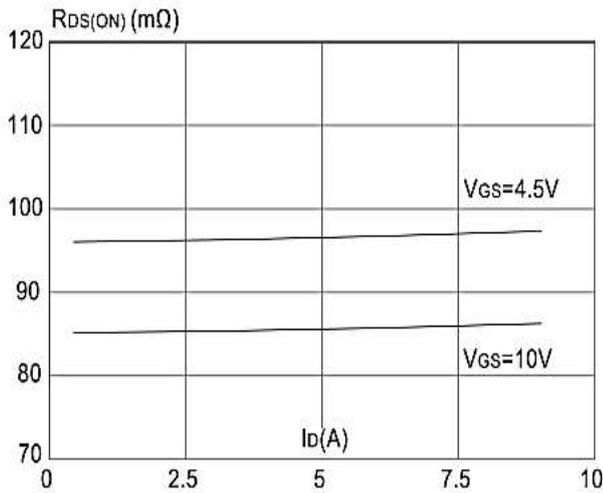
**Typical Characteristics**



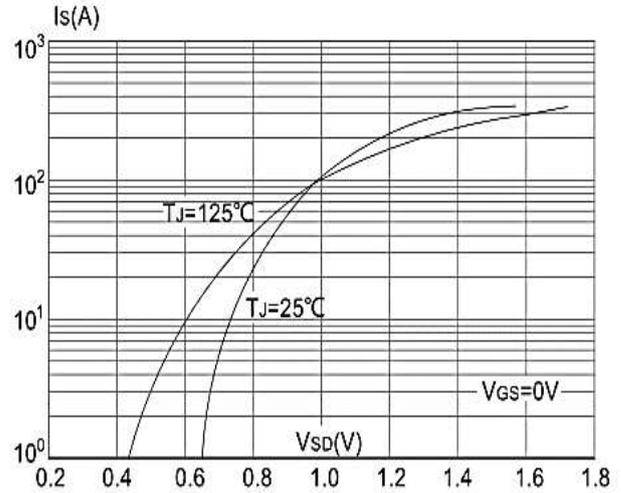
**Figure 1: Output Characteristics**



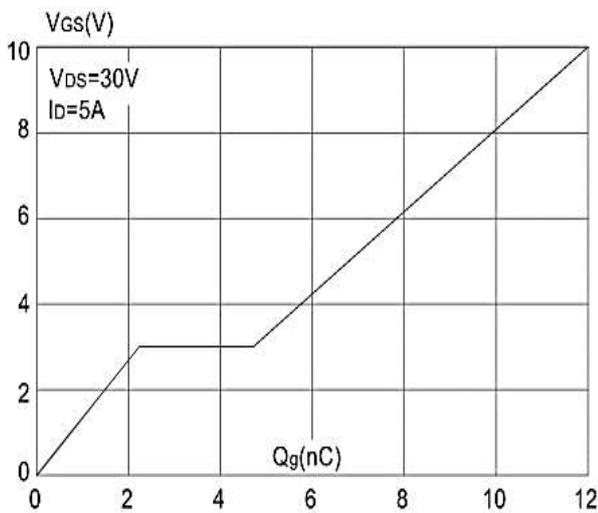
**Figure 2: Typical Transfer Characteristics**



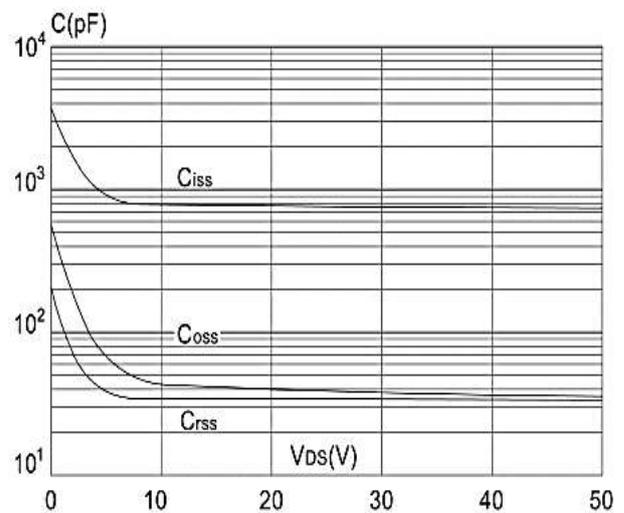
**Figure 3: On-resistance vs. Drain Current**



**Figure 4: Body Diode Characteristics**

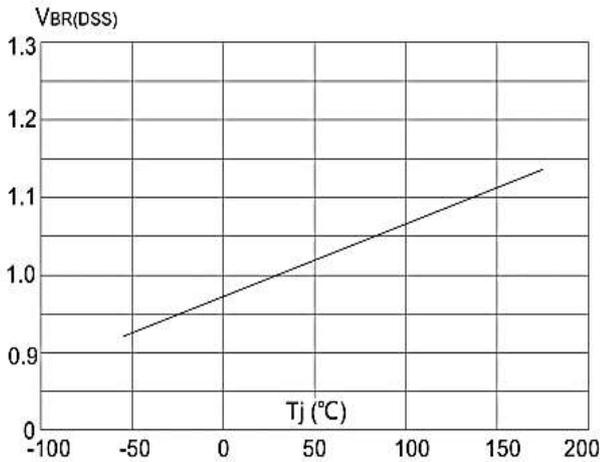


**Figure 5: Gate Charge Characteristics**

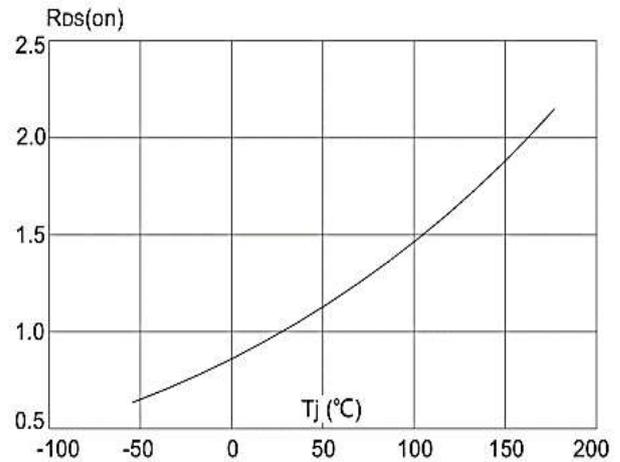


**Figure 6: Capacitance Characteristics**

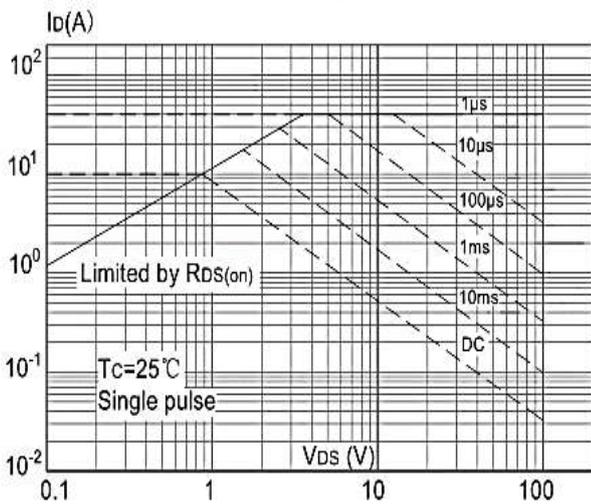
**Ratings and Characteristic Curves**



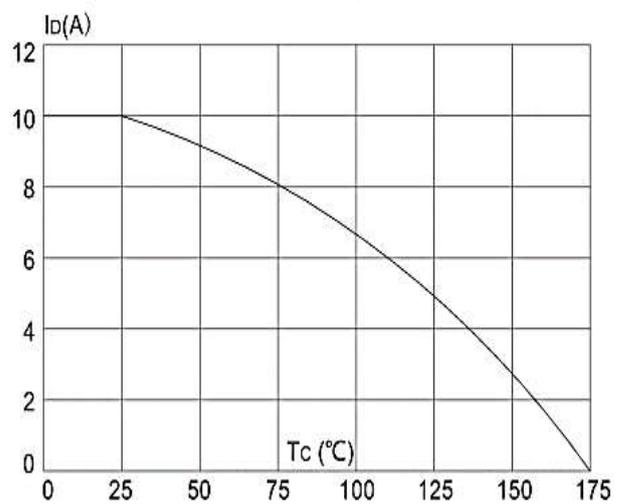
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



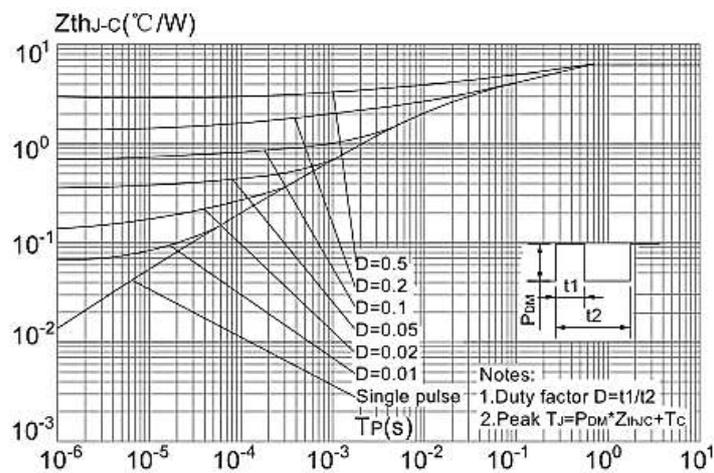
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area**

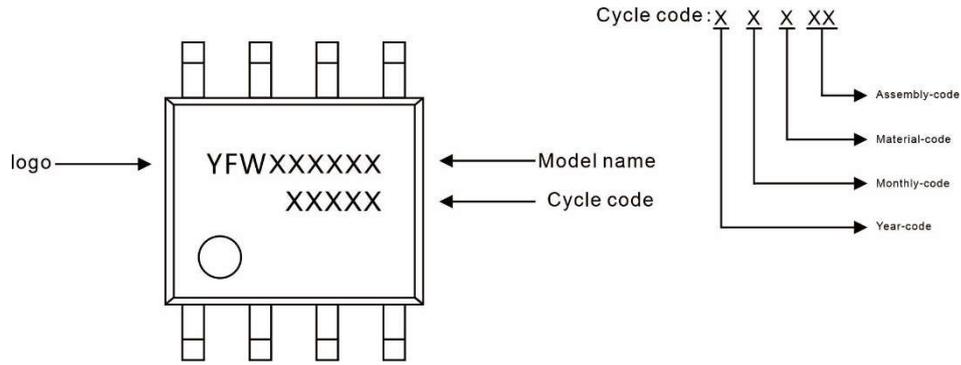


**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



**Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case**

**Marking Diagram**



**Ordering information**

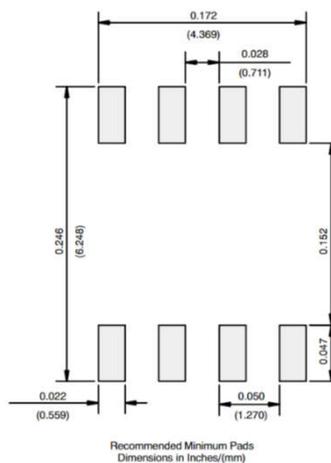
Package	Packing Description	Packing Quantity
SOP-8	Tape/Reel, 13" reel	3000PCS/Reel 30000PCS/Carton

**Package Dimensions**

**SOP-8**

Dim	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
A2	1.35	1.50	0.053	0.059
b	0.35	0.55	0.014	0.022
c	0.15	0.25	0.006	0.010
D	4.80	5.00	0.189	0.197
D1	3.10	3.50	0.122	0.138
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
E2	2.20	2.60	0.087	0.102
e	1.27 (BSC)		0.050 (BSC)	
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

**The recommended mounting pad size**



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